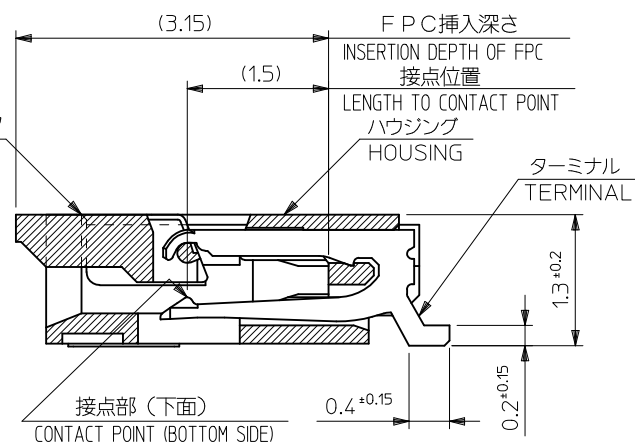
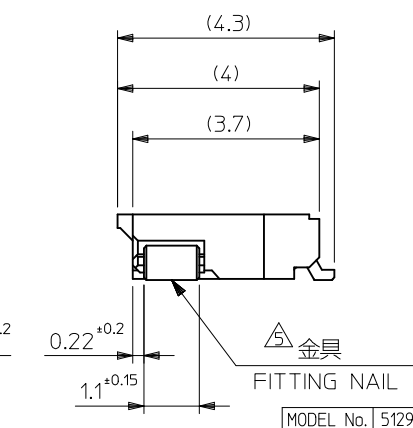
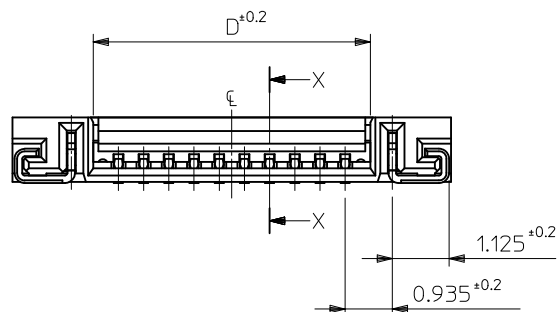
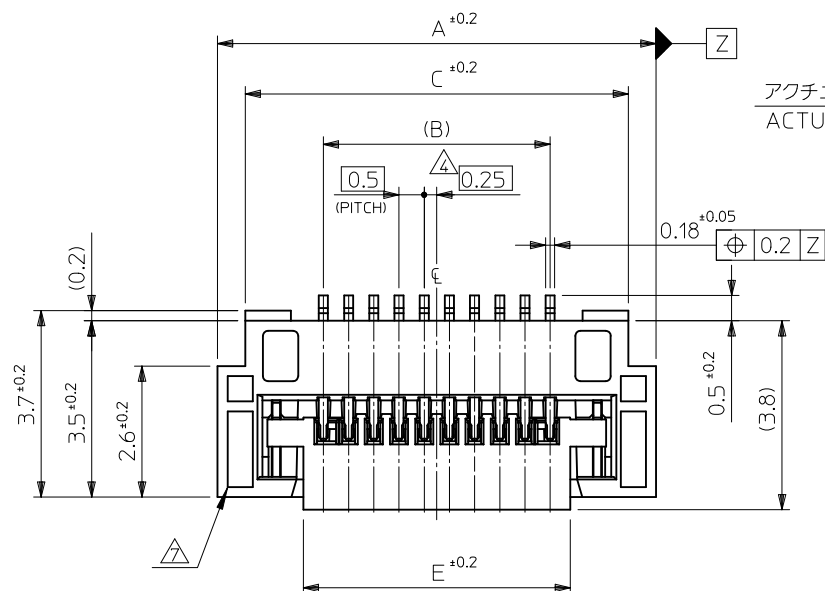
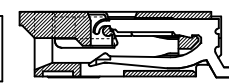
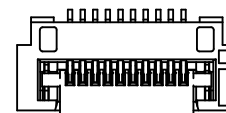


SECT. X-X

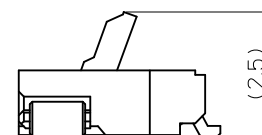
-30 極以上-
30 Ckt. OR MORE



SECT. X-X

-29極以下-
29 Ckt. OR LESS

△外觀形狀 APPEARANCE FORM



(アクチュエータが開口した状態)
(WHEN ACTUATOR IS OPENED)

	30.3	30.5	32.6	29.5	33.7	51296-6093	51296-6041	60
	25.3	25.5	27.6	24.5	28.7	51296-5093	4 -5041	50
	22.8	23.0	25.1	22.0	26.2	51296-4593	-4541	45
	20.3	20.5	22.6	19.5	23.7	51296-4093	-4041	40
	17.3	17.5	19.6	16.5	20.7	51296-3493	-3441	34
	9.3	9.5	11.6	8.5	12.7	51296-1893	-1841	18
	7.3	7.5	9.6	6.5	10.7	51296-1493	7 -1441	14
	6.3	6.5	8.6	5.5	9.7	51296-1293	-1241	12
	4.3	4.5	6.6	3.5	7.7	51296-0893	51296-0841	8
41	E	D	C	B	A	EMBOSSED TAPE	製品番号 MATERIAL No.	極数 Ck
						ORDER No. オート番号		

REVISED EC NO: J2011-0996 DRAWN: KMURAKAMI 2010/11/01 CHKD: T APPR: KMORIKAWA 2011/02/15	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY K. MURAKAMI	DATE 2004/02/06	TITLE 0.5 FPC CONN EASY ON HGT=1.3MM ASSY -LEAD FREE-				
		10 OVER 30 UNDER	± ---	CHECKED BY S. A HARA	DATE 2004/02/06					
		30 OVER	± ---	APPROVED BY M. SASAO	DATE 2004/02/06	MOLEX INCORPORATED				
		ANGULAR ± --- °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-51296-007		1 OF 2		
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

F

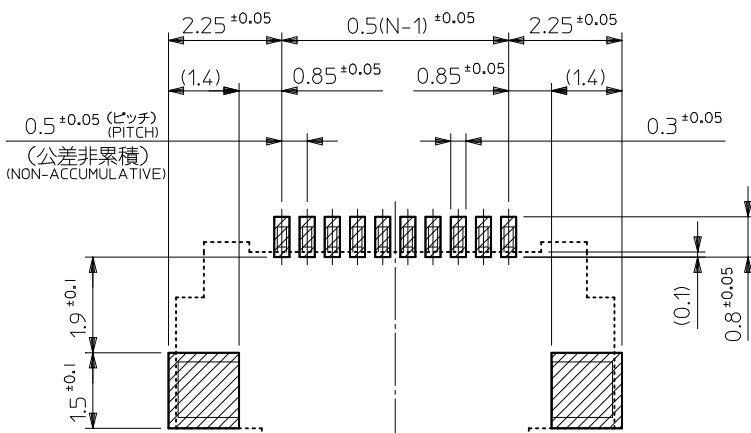
E

D

C

B

A

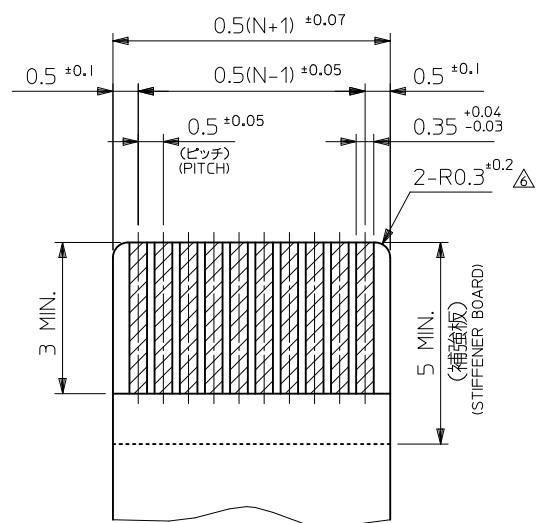


参考基板レイアウト
P.C. BOARD PATTERN
DIMENSION (REF.)
(マウント面)
(MOUNTING SIDE)
コネクタ位置
CONNECTOR POSITION

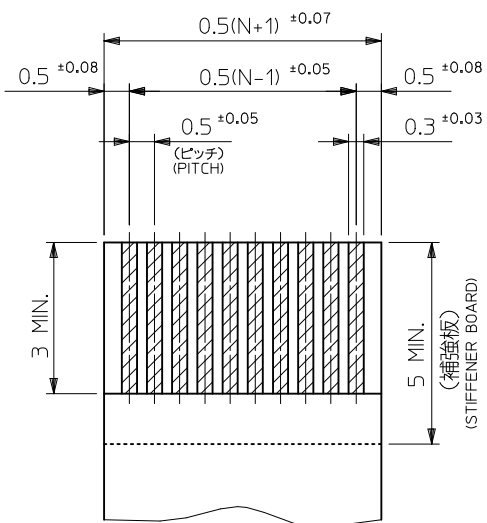
注記 NOTES

1. 使用材料 MATERIAL
- ハウジング : 液晶ポリマー ガラス充填, UL94V-0 (ベージュ)
HOUSING LIQUID CRYSTAL POLYMER GLASS FILLED, UL94V-0 (BEIGE)
- アクチュエータ : ポリアミド 9T ガラス充填, UL94V-0 (黒)
ACTUATOR POLYAMIDE 9T GLASS FILLED, UL94V-0 (BLACK)
- ターミナル : リン青銅 (t=0.18)
TERMINAL PHOSPOR BRONZE
- 金具 : リン青銅 (t=0.15)
FITTING NAIL PHOSPOR BRONZE
2. メッキ仕様 PLATING
- ターミナル TERMINAL
- 錫ビスマスメッキ 1.0マイクロメートル以上
ニッケル下地 1.0マイクロメートル以上
TIN-BISMUTH (Sn-Bi) 1.0 MICROMETER MINIMUM
OVER NICKEL PLATING 1.0 MICROMETER MINIMUM
- 金具 FITTING NAIL
- 錫メッキ 1.0マイクロメートル以上
ニッケル下地 1.0マイクロメートル以上
TIN (Sn) 1.0 MICROMETER MINIMUM
OVER NICKEL (Ni) PLATING 1.0 MICROMETER MINIMUM

3. エンボステープ梱包時は、アクチュエータが閉じた状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO.51296-***41 SHOULD BE CLOSED.
- 偶数極に適用。
APPLY FOR EVEN CIRCUIT.
- パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF PCB PATTERN.
- R0.3は、FPC導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.
- 極数によりハウジング形状が異なるので注意のこと。
THE HOUSING SHAPE IS DIFFERENT ACCORDING TO THE CIRCUIT.
- 8 本製品は51296-***31の鉛フリー製品である。
THIS PRODUCT IS LEAD FREE OF 51296-***31.



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3 ±0.05)
(THICKNESS: 0.3 ±0.05)



適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3 ±0.05)
(THICKNESS: 0.3 ±0.05)

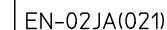
FPC/FFCについて:

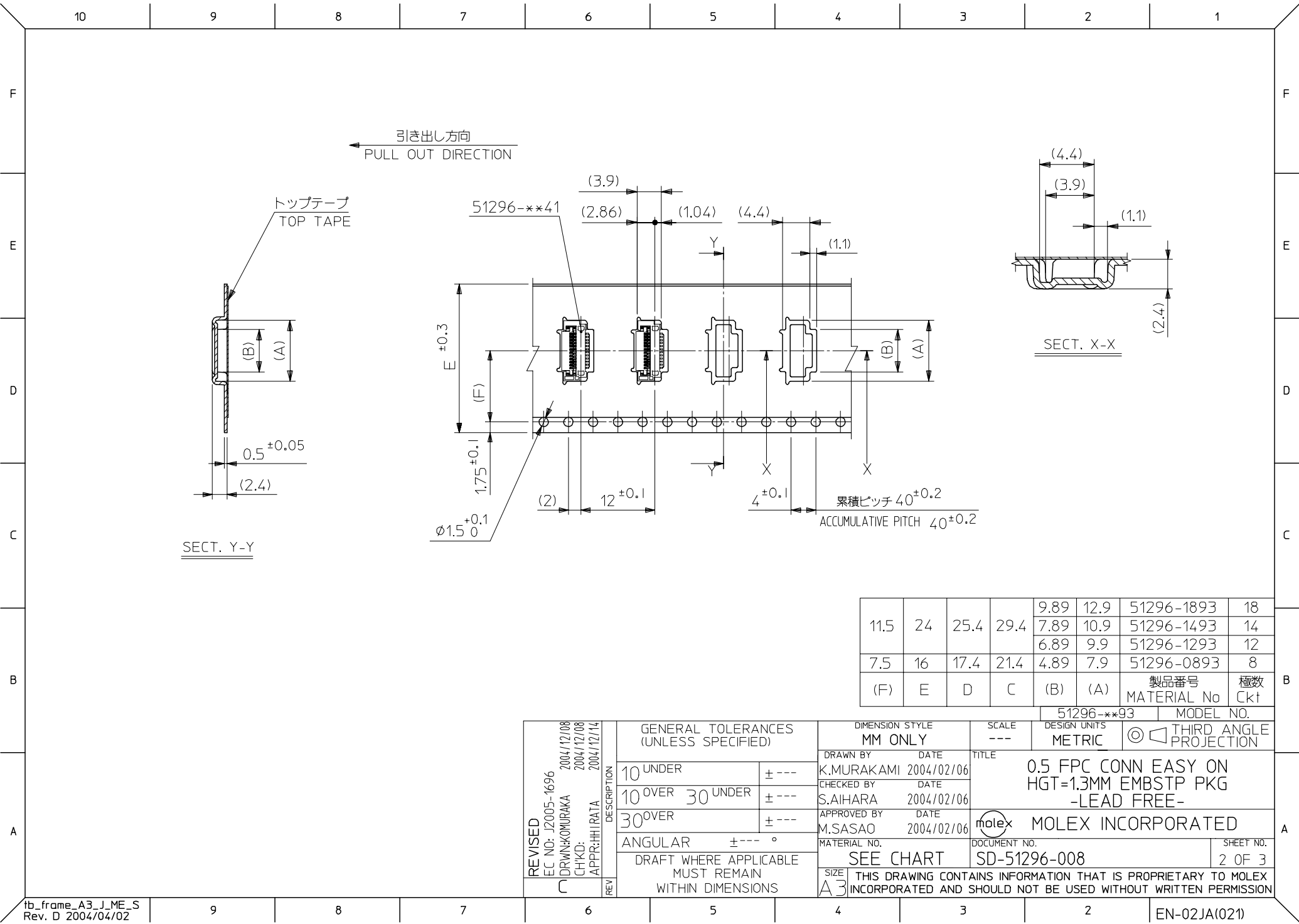
打抜き方向は導体側から補強板側を推奨いたします。
導体部については軟銅箔35マイクロメートルまたは50マイクロメートルを推奨致します。
ABOUT FPC/FFC
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPEC :
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER

FPCについて:

補強フィルム材質はポリイミドを推奨します。
接着剤は熱硬化接着剤を推奨します。
ABOUT FPC
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

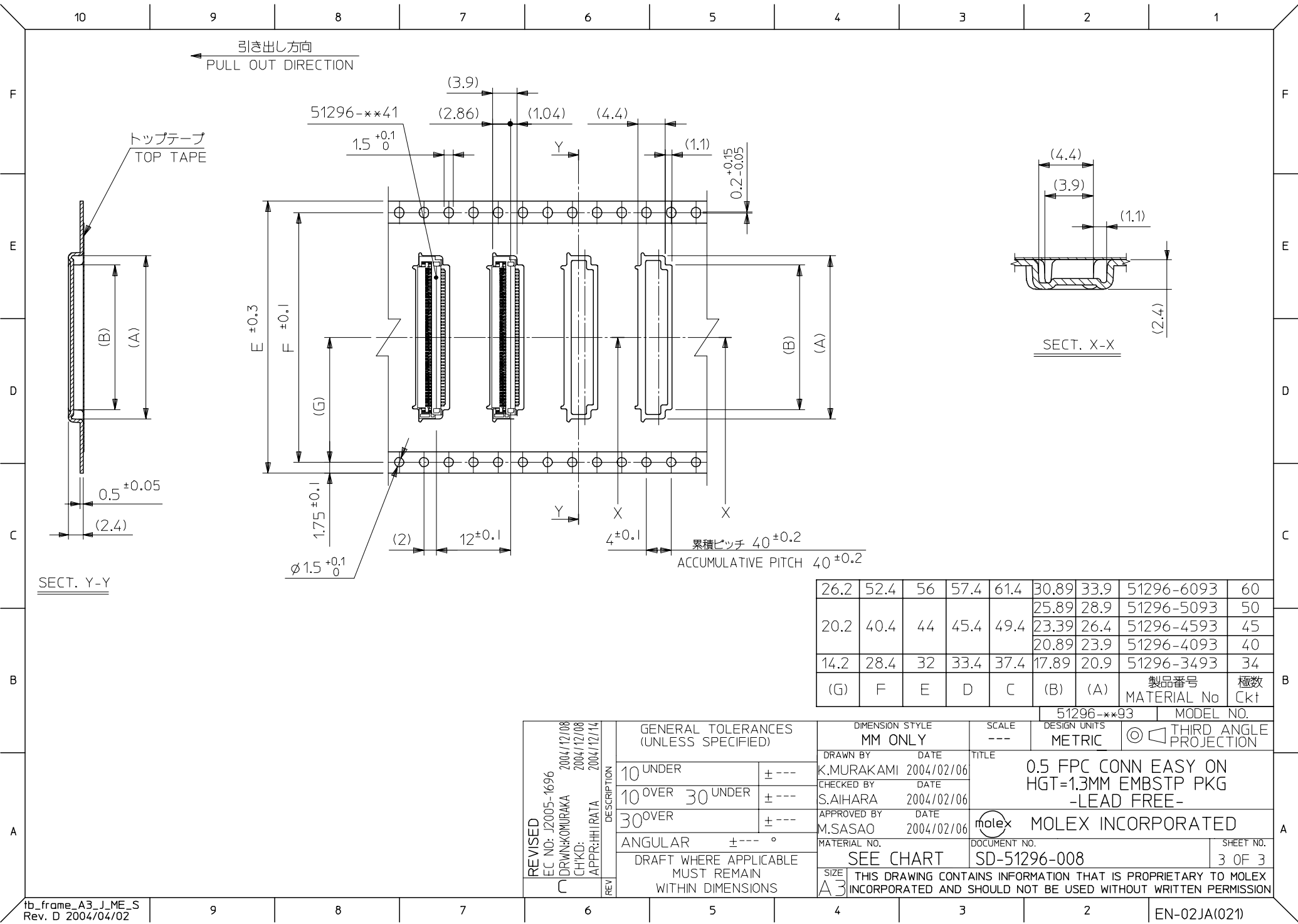
REVISED EC NO: J2011-0996 DRAWN: K. MURAKAMI CHKD: CHIKO APPR: K. MORIKAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	MODEL No. 51296-***41		
				MM ONLY		---	METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY K. MURAKAMI	DATE 2004/02/06	TITLE 0.5 FPC CONN EASY ON HGT=1.3MM ASSY -LEAD FREE-				
		10 OVER 30 UNDER	± ---	CHECKED BY S. AIHARA	DATE 2004/02/06					
		30 OVER	± ---	APPROVED BY M. SASAO	DATE 2004/02/06	MOLEX MOLEX INCORPORATED				
	ANGULAR ± --- °	MATERIAL NO.		DOCUMENT NO.		SHEET NO.				
	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE		SD-51296-007					2 OF 2
SIZE A3			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

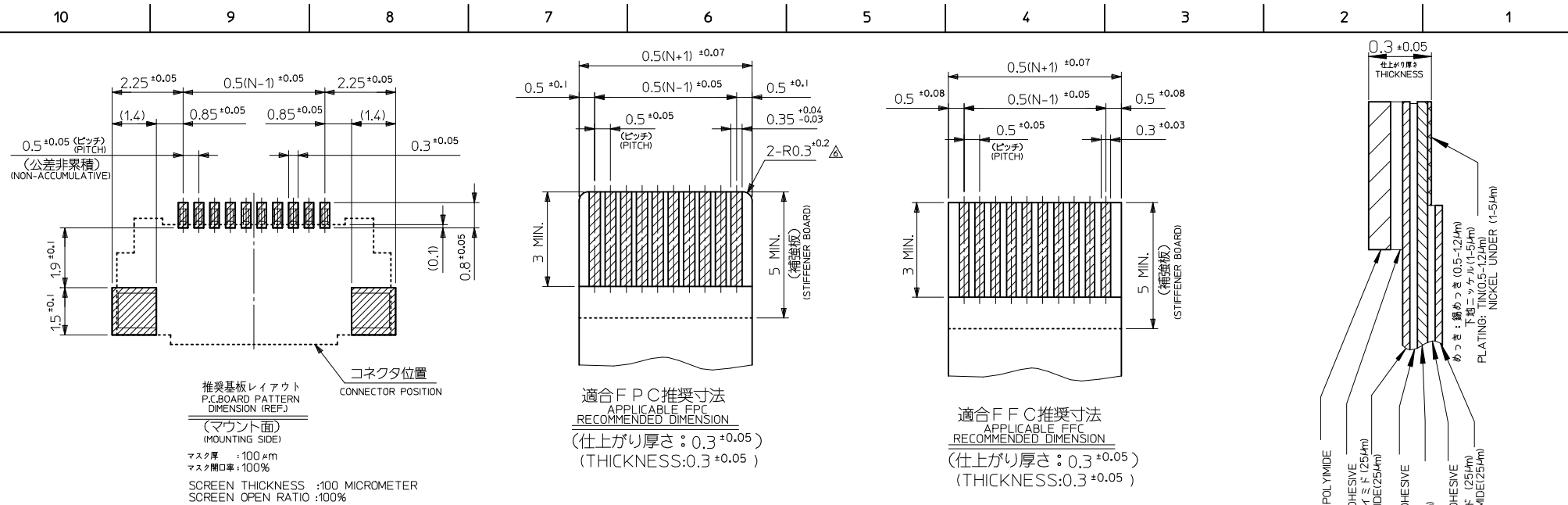




11.5	24	25.4	29.4	9.89	12.9	51296-1893	18
				7.89	10.9	51296-1493	14
				6.89	9.9	51296-1293	12
7.5	16	17.4	21.4	4.89	7.9	51296-0893	8
(F)	E	D	C	(B)	(A)	製品番号 MATERIAL No	極数 Ckt

REVISED EC NO: J2005-1696 DRAWN: K.MURAKAMI CHKD: S.AIHARA APPR: H.HIRATA	DESCRIPTION 2004/12/08 2004/12/08 2004/12/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY K.MURAKAMI	DATE 2004/02/06	TITLE 0.5 FPC CONN EASY ON HGT=1.3MM EMBSTP PKG -LEAD FREE-				
		10 OVER 30 UNDER	± ---	CHECKED BY S.AIHARA	DATE 2004/02/06					
		30 OVER	± ---	APPROVED BY M.SASAO	DATE 2004/02/06	MOLEX MOLEX INCORPORATED				
		ANGULAR ± --- °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-51296-008		2 OF 3		
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				





注記 NOTES

1. 使用材料 MATERIAL
- ハウジング : 液晶ポリマー(LCP)、ベージュ、ガラス充填、UL94V-0
HOUSING LIQUID CRYSTAL POLYMER, BEIGE, GLASS FILLED, UL94V-0
- アクチュエータ : ポリアミド(PPS)、黒、ガラス充填、UL94V-0
ACTUATOR POLYAMIDE, BLACK, GLASS FILLED, UL94V-0
- ターミナル : リン青銅 (t=0.18)
TERMINAL PHOSPOR BRONZE
- 金具 : リン青銅 (t=0.15)
FITTING NAIL PHOSPOR BRONZE
2. メッキ仕様 PLATING
- ターミナル TERMINAL
- 鍍銀ビスマスマッキ (1.0μm以上)
TIN SILVER BISMUTH PLATING (1.0 MICROMETER MINIMUM)
- 下地 : ニッケルめっき(1.0μm以上)
UNDER PLATING:NICKEL PLATING (1.0 MICROMETER MINIMUM)
- 金具 FITTING NAIL
- 鍍メッキ (1.0μm以上)
TIN PLATING (1.0 MICROMETER MINIMUM)
- 下地 : ニッケルめっき(1.0μm以上)
UNDER PLATING:NICKEL PLATING (1.0 MICROMETER MINIMUM)
3. エンボステープ梱包時は、アクチュエータが閉じた状態とする。
IN THE PACKAGE,ACTUATOR SHOULD BE CLOSED.
- △ 偶数極に適用。
APPLY FOR EVEN CIRCUIT.
- △ バターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF PCB PATTERN.
- △ R0.3は、FPC導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.
- △ 極数によりハウジング形状が異なるので注意のこと。
THE HOUSING SHAPE IS DIFFERENT ACCORDING TO THE CIRCUIT.
8. テール及び金具の平坦度は、0.1ミリメートル以下とする。
TAIL AND FITTING NAIL COPLANARITY TO BE 0.1 MILLIMETERS.
9. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

FPCについて:

抜き方向は、導体側から補強板側を推奨致します。

補強フィルム材質は、ポリイミドを推奨致します。

接着剤は熱硬化接着剤を推奨します。

尚、接着剤の接点部への付着は導通不良の原因になりますので、

染み出しが無い様お願い致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFNER SIDE

RECOMMENDED MATERIAL : STIFFENER FILM POLYIMIDE

BONDING AGENT : THERMOSETTING AGENT

PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE
CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

FFC/FPCについて:

打抜き方向は導体側から補強板側を推奨致します。

導体部については軟銅箔35μmまたは50μmを推奨致します。

ABOUT FFC/FPC:

RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.

RECOMMENDED CONDUCTOR SPECIFICATION:
THICKNESS OF SOFT COPPER FOIL: 35MICROMETER OR 50 MICROMETER

FPC構成推奨仕様
STRUCTURE OF FPC

SEE SHEET 1 OF 2 EC NO: J2014-0096 DRAWN: AISHI 2013/07/18 CHKD: TAKAHASHI 2013/07/18 APPR: YNOGAWA 2013/08/19	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	AISHI	2012/09/19	TITLE 0.5MM FPC CONN F/F E/O HOUSING ASSY				
		10 OVER 30 UNDER	± ---	CHECKED BY	DATE					
		30 OVER	± ---	APPROVED BY	DATE					
		ANGULAR	± --- °	KMORIKAWA		2013/03/15	molex			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		DOCUMENT NO.					
			SEE SHEET1		SD-51296-017		2 OF 2			
REV			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							